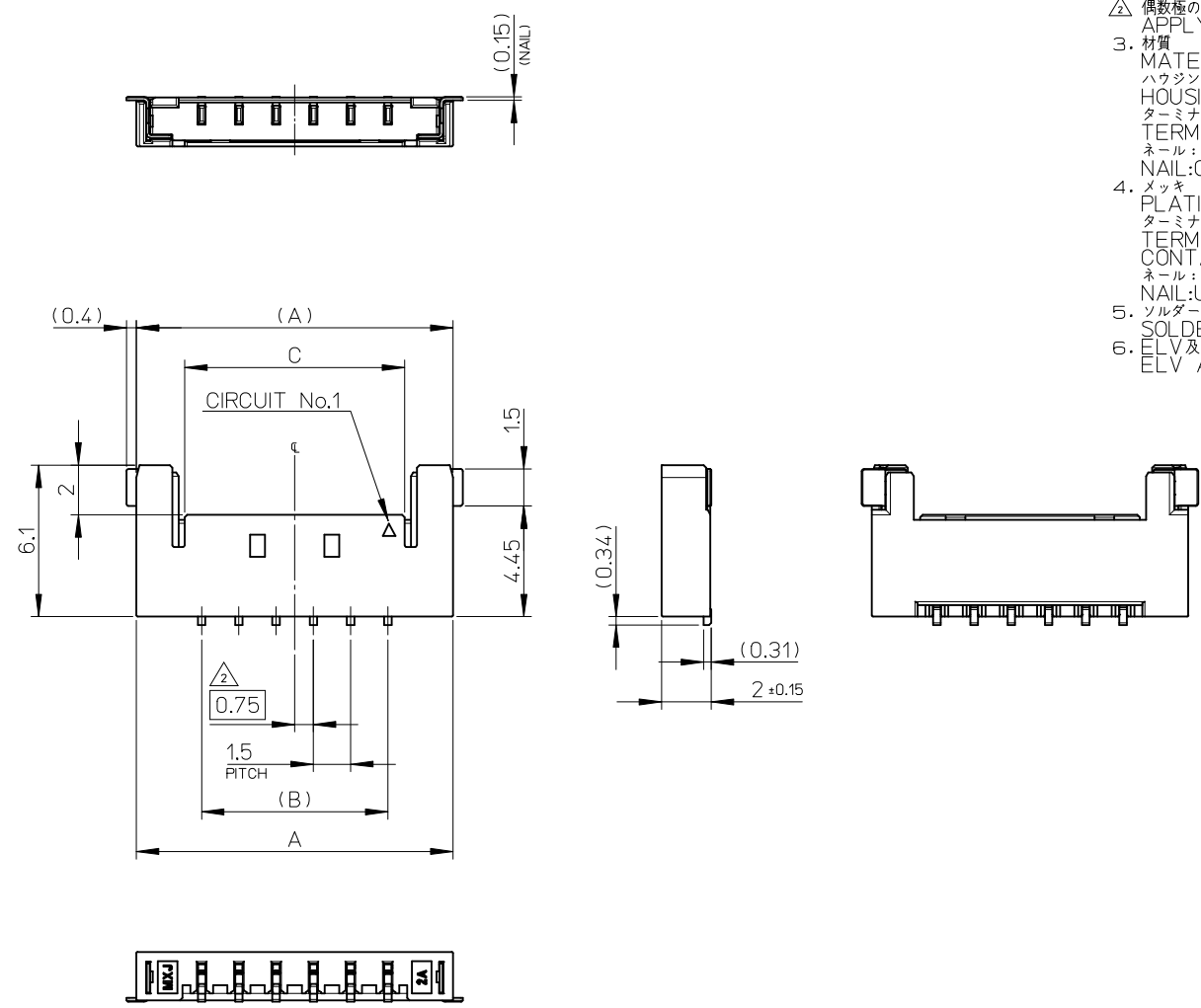


NOTE.

1. 嵌合相手: 504051****
MATE WITH: 504051****
△ 偶数極の製品に適用
APPLY EVEN CIRCUIT PRODUCTS.
2. 材質
MATERIAL
ハウジング: 耐熱性樹脂 UL94-V0 BLACK
HOUSING: HEATPROOF RESIN UL94-V0 BLACK
ターミナル: 銅合金
TERMINAL: COPPER ALLOY
ネール: 銅合金
NAIL: COPPER ALLOY
3. メッキ
PLATING
ターミナル: 下地 Niメッキ 1μm MIN., コンタクト・半田付け部 Auメッキ 0.1μm MIN.
TERMINAL: UNDER NICKEL PLATING 1μm MIN.
CONTACT AND TAIL GOLD PLATING 0.1μm MIN.
ネール: 下地 Niメッキ 1μm MIN., Snメッキ 1μm MIN.
NAIL: UNDER NICKEL PLATING 1μm MIN., TIN PLATING 1μm MIN.
4. ソルダーテイルとネールの平坦度: 0.08mm MAX.
SOLDER TAIL AND FITTING NAIL COPLANARITY: 0.08mm MAX.
5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.



17.85	16.5	21.75	5040501291	12
14.85	13.5	18.75	5040501091	10
11.85	10.5	15.75	5040500891	8
10.35	9.0	14.25	5040500791	7
8.85	7.5	12.75	5040500691	6
7.35	6.0	11.25	5040500591	5
5.85	4.5	9.75	5040500491	4
C	B	A	EMBOSSED PACKAGE	CIRCUIT
			ORDER No.	
CONNECTOR SERIES No. : 504050**91				

REVISED EC NO: J2016-0297 DRWN: TAKAIKE 2015/09/18 CHKD: KASAKAWA 2015/10/02 APPR: NUKITA 2015/10/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	THANYU	2012/03/29	1.5 WIRE TO BOARD CONN. R/A H=2MM HEADER ASS'Y		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
	1.0 OVER 10 UNDER	±0.2	KASAKAWA	2012/03/29			
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.	SHEET NO.		
30 OVER	±0.3	YOITO	2012/04/18	SD-504050-001	1 OF 2		
ANGULAR ±3°		MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

D

C

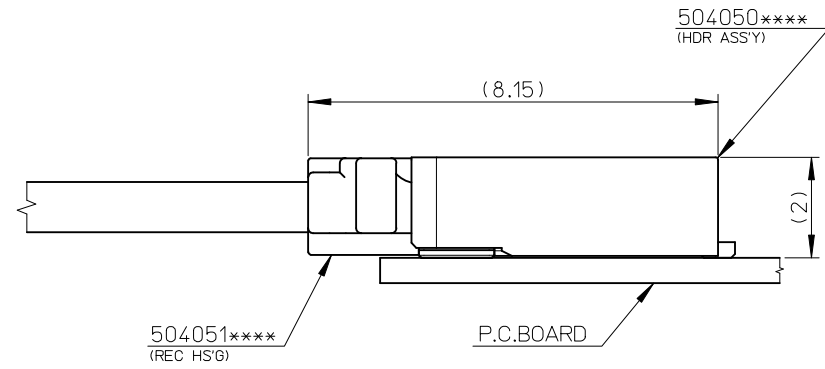
B

A

504050****
(HDR ASS'Y)

(8.15)

(2)

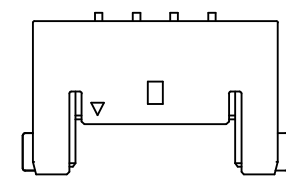


504051****
(REC HS'G)

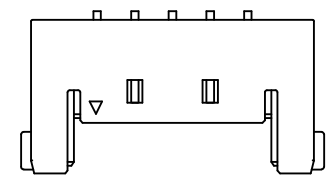
P.C. BOARD

MATED CONNECTORS

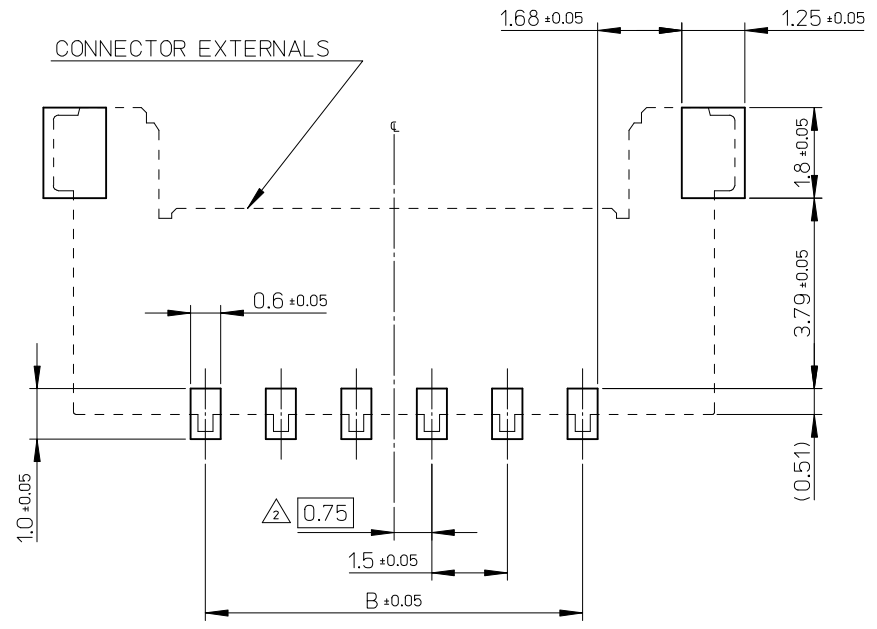
NUMBER of LOCK Ⓞ



4 CIRCUITS



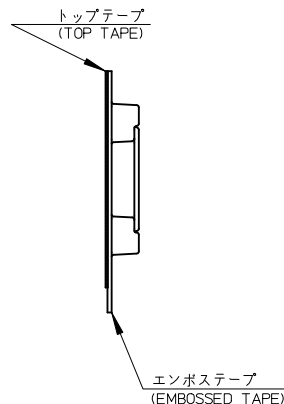
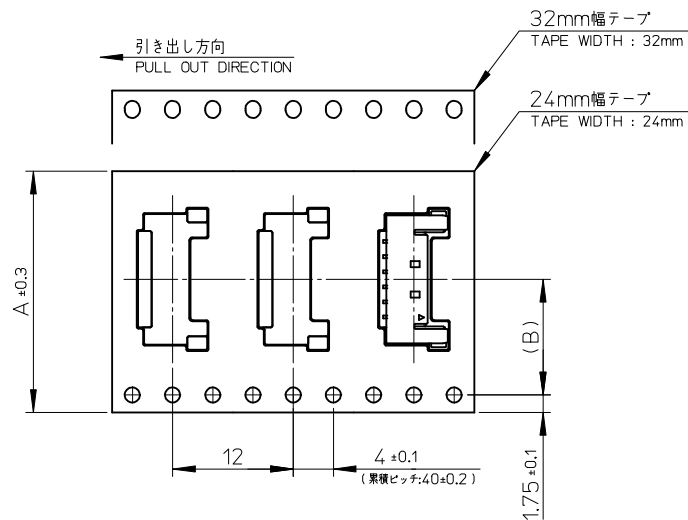
5-12 CIRCUITS



RECOMMENDED PATTERN LAYOUT (REF.)

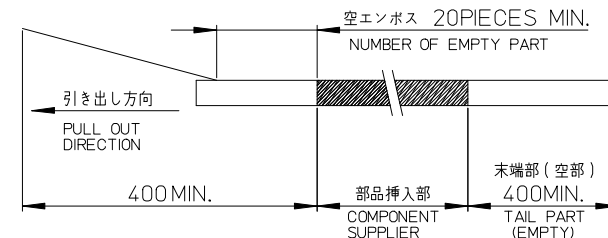
REVISED	EC NO: J2016-0297	DRWN: TAKAIKE 2015/09/18	CHKD: KASAKAWA 2015/10/02	APPR: NUKITA 2015/10/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
					0.25 UNDER	± 0.03	MM ONLY	10:1	METRIC		
G	REV	DESCRIPTION	0.25 OVER	0.5 UNDER	± 0.05	DRAWN BY	DATE	TITLE	1.5 WIRE TO BOARD CONN. R/A H=2MM HEADER ASS'Y		
			0.5 OVER	1.0 UNDER	± 0.1	THANYU	2012/03/29				
			1.0 OVER	10 UNDER	± 0.2	CHECKED BY	DATE		molex		
			10 OVER	30 UNDER	± 0.25	KASAKAWA	2012/03/29				
			30 OVER		± 0.3	APPROVED BY	DATE		SD-504050-001		
			ANGULAR	± 3 °		YOITO	2012/04/18				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			DOCUMENT NO.	SHEET NO.
						A3					2 OF 2

9 8 7 6 5 4 3 2 1



NOTE

1. 梱包数量: 2700個 / リール
NUMBER OF CONNECTORS : 2700 PIECES/REEL
2. リードテープ長さ
LEAD TAPE LENGTH

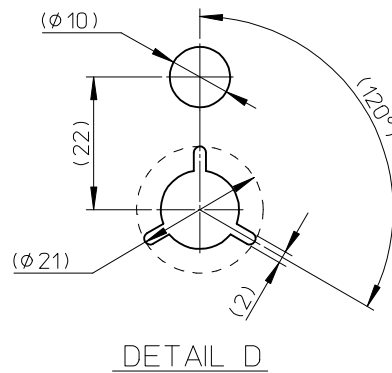
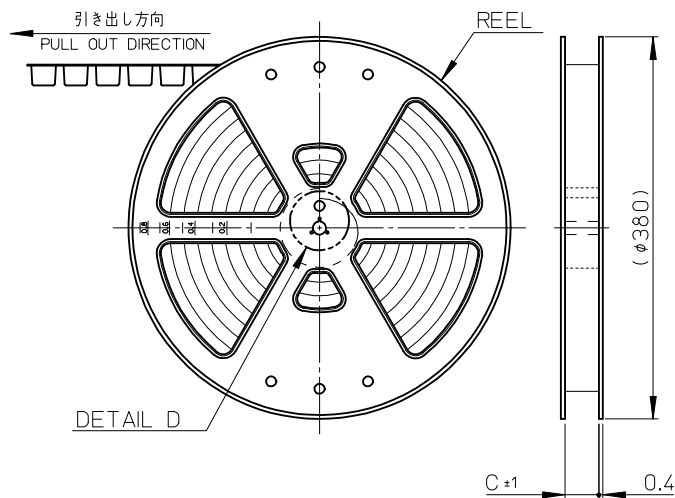


3. 材料
MATERIALS
キャリアテープ: ポリスチレン
CARRIER TAPE : POLYSTYRENE
トップテープ: ポリエステル, ポリエチレン, ポリエチレンテレフタレート
TOP TAPE : POLYESTER, POLYETHLENE, POLYETHYLENE TEREPHTHALATE
リール: ポリスチレン (リサイクル材を含む)
REEL : POLYSTYRENE (RECYCLE MATERIAL CONTAINED)

4. 製品詳細寸法については、RSD-504050-001を参照して下さい。
PLEASE REFER TO RSD-504050-001 FOR THE DETAILED DIMENSION OF THE CONNECTOR.

5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.

6. トップテープの剥離強度については、IEC60286-3に準拠の事。
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.



45.5	20.2	44	5040501291	12
33.5	14.2	32	5040501091	10
33.5	14.2	32	5040500891	8
25.5	11.5	24	5040500791	7
25.5	11.5	24	5040500691	6
25.5	11.5	24	5040500591	5
25.5	11.5	24	5040500491	4
C	B	A	ORDER No.	CIRCUIT
WIDTH OF TAPE				

REVISED EC NO: J2015-1139 2015/03/05 DRWNK:CHIKANO 2015/03/05 CHKD:KASAKAWA 2015/03/06 APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	±0.03	DRAWN BY THANYU	DATE 2012/03/29	TITLE EMBOSSED TAPE PACKAGE FOR 504050-**** (1.5 W/B CONN. H=2MM) molex DOCUMENT NO. SD-504050-002 SHEET NO. 1 OF 1			
		0.25 OVER 0.5 UNDER	±0.05	CHECKED BY KASAKAWA	DATE 2012/03/29				
		0.5 OVER 1.0 UNDER	±0.1	APPROVED BY YOITO	DATE 2012/04/18				
1.0 OVER 10 UNDER	±0.2	MATERIAL NO.							
10 OVER 30 UNDER	±0.25	ANGULAR ±3 °		SEE CHART					
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				